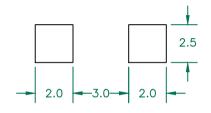
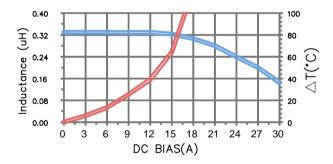
## MGV0502R33M-10

## PHYSICAL DIMENSIONS:

Α	5.50	$\pm$	0.50
В	5.10	±	0.30
С	2.00	±	0.30
D	1.50	±	0.30
Ε	1.20	±	0.50

## LAND PATTERNS FOR REFLOW SOLDERING

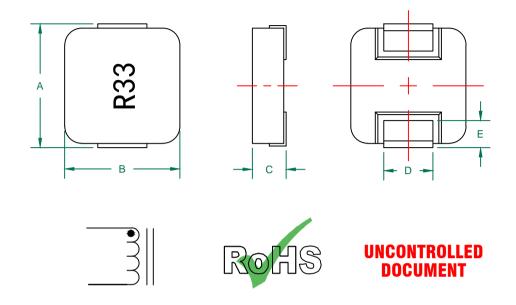




## ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 100 KHz/0.25V ± 20%	0.264	0.330	0.396
DCR $(\Omega)$			0.0082

Saturation Current <sup>3</sup> Isat (A)	25.00
Temperature Rise Current Irms <sup>4</sup> (A)	12.00



NOTES: UNLESS OTHERWISE SPECIFIED

- 1.COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 3.DEFINITION OF SATURATION CURRENT (ISAT): DC CURRENT AT WHICH THE INDUCTANCE DROPS  $\leq 25\%$  FROM ITS VALUE WITHOUT CURRENT (Ta=25 $\pm$ 5°C).
- 4.DEFINITION OF TEMPERATURE RISE CURRENT (IRMS): DC CURRENT THAT CAUSES THE TEMPERATURE RISE ( $\Delta T \leq 40^{\circ}$ C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm.			This print is the property of Laird						
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				reserved.					
D	UPDATE LOGO	04/22/15	QIU	PROJECT/PART NUMBER:	- 11	EV	PART TY	PE: WER	DRAWN BY:
С	CHANGE NOTE 2.3.4	09/24/12	QIU	MGV0502R33M-10	1	ט		CTOR	QIU
В	REVISE DIMENSIONS	06/27/12		DATE: 04/25/12	CAL	E: NI	TS	SHEET:	
Α	ORIGINAL DRAFT	04/25/12	QU	, ,	OOL		13		
REV	DESCRIPTION	DATE	INT			•	-	1	of 1